

THE FUTURE OF POWER INDUCTORS: MINIMAL LOSSES AND COMPACT DESIGNS

Theo Ritzmann – Technical Lead PM Passive Power

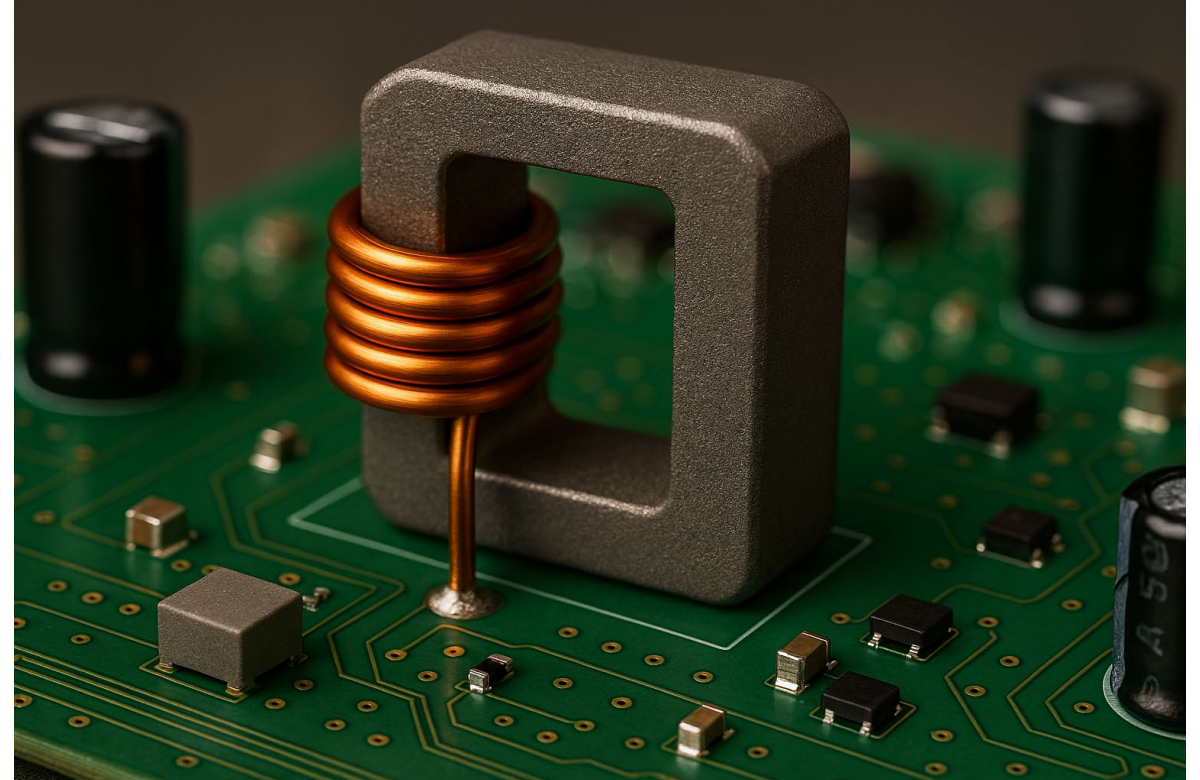
WÜRTH ELEKTRONIK MORE THAN YOU EXPECT

AGENDA

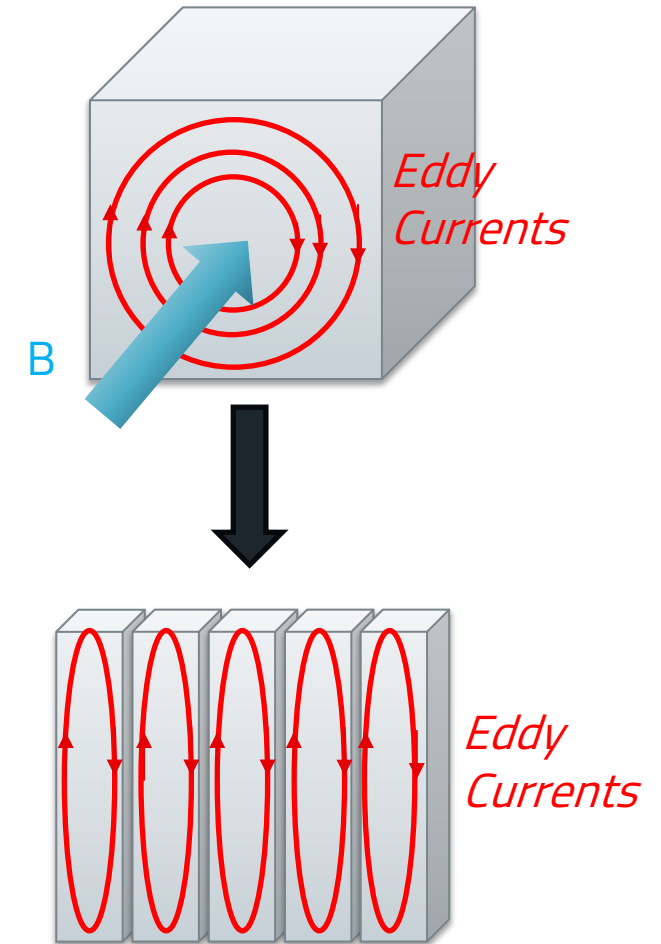
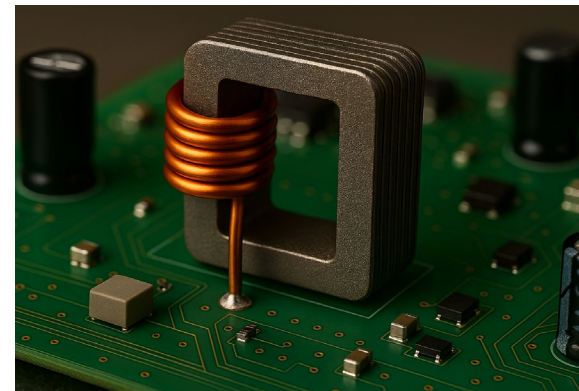
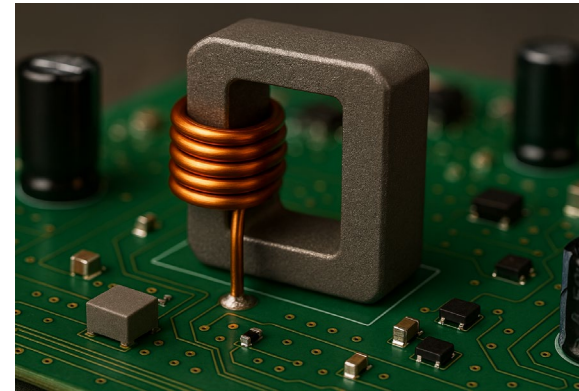
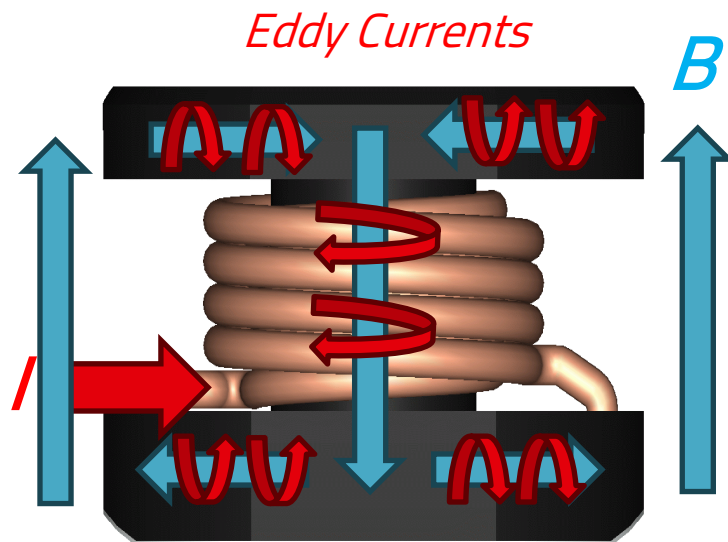
- Early 20th century
 - Inductors based on massive iron cores
- 1970s / 1980s
 - Inductors based on ferrites
- 1990s / 2000s
 - Inductors based on iron/alloy powders
- Present / Future Trends
 - Inductors based on ...

EARLY 20TH CENTURY

- Applications in the low frequency range up to single digit kHz
- Inductors based on massive iron cores
- **Advantages** of these cores
 - High permeability and saturation flux density
- **Disadvantages** of these cores
 - Electrically conductive

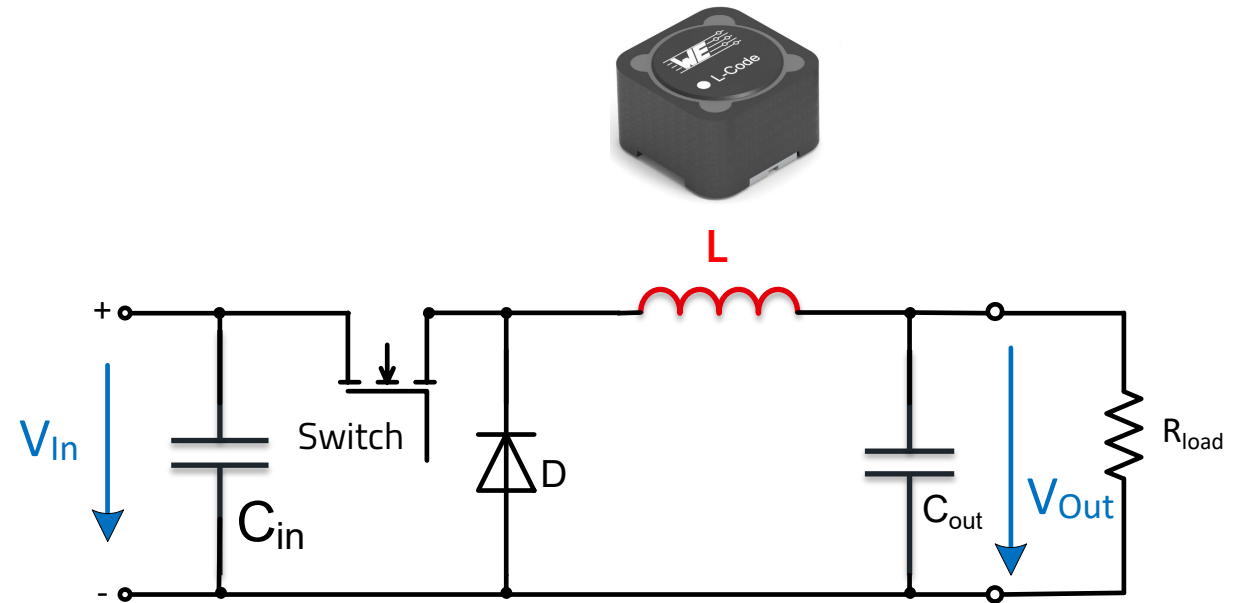


EDDY CURRENTS AND PREVENTION



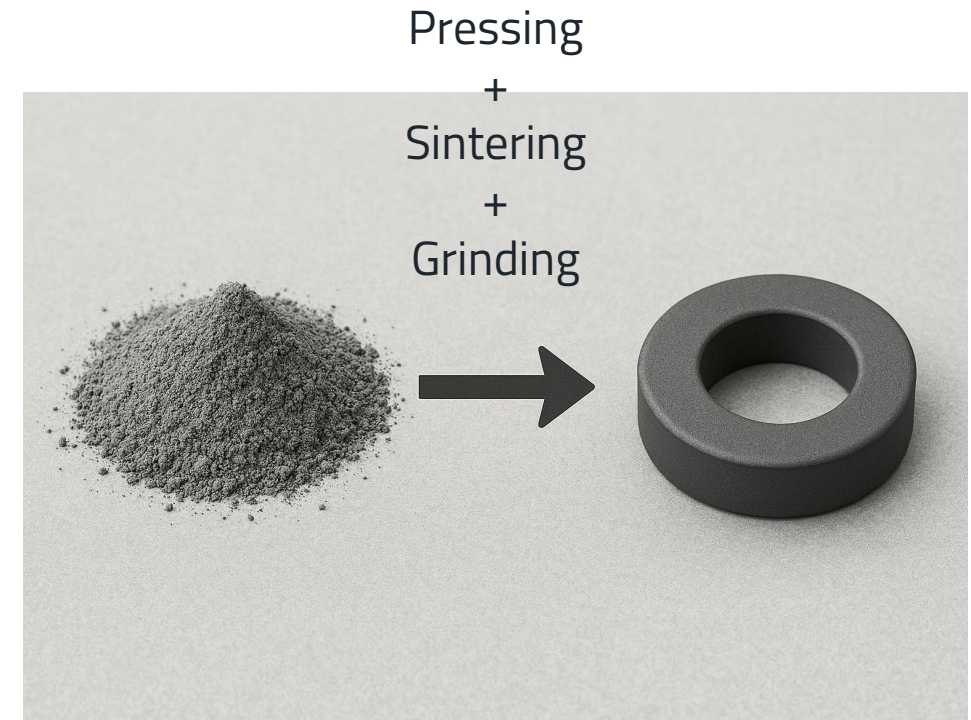
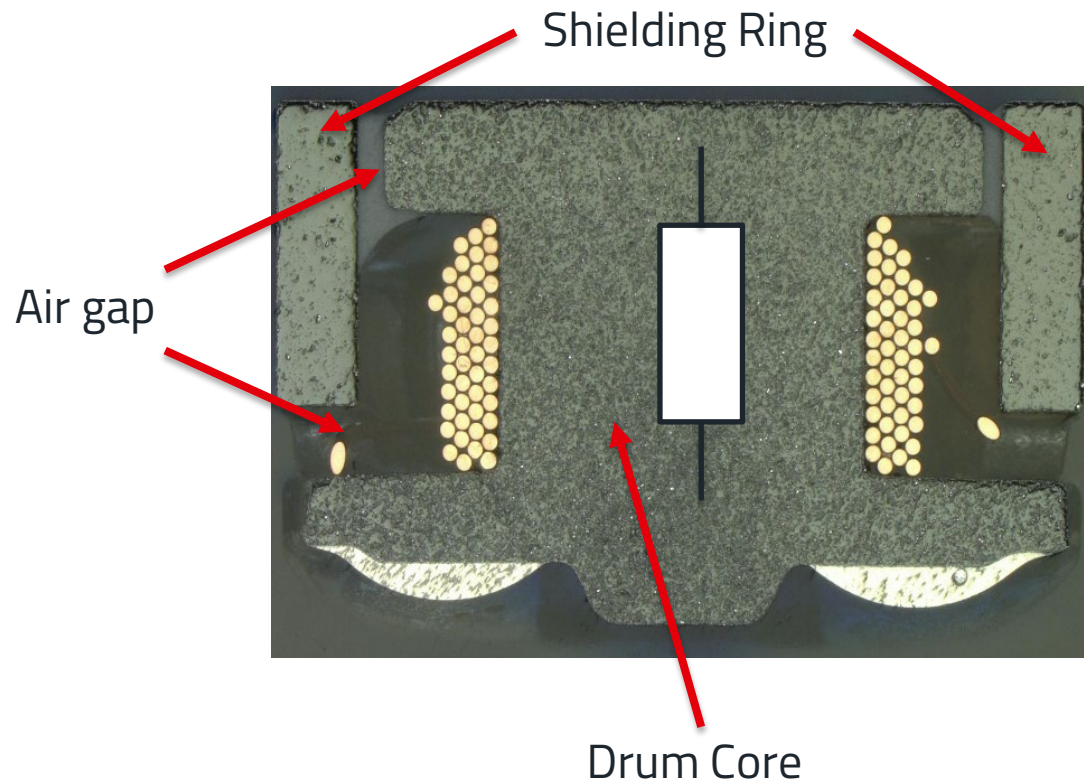
1970S / 1980S

- Switch mode power supplies based on semiconductor technology
- frequency range from double digit to triple digit kHz
- Need for lower AC losses
- Ferrite power inductors
- Also popular material for EMC inductors



FERRITE BASED POWER INDUCTORS

Material & Design



FERRITE BASED POWER INDUCTORS

Products

WE-TI



WE-PD2



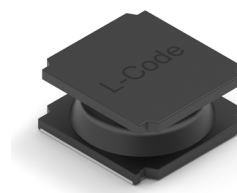
WE-TPC



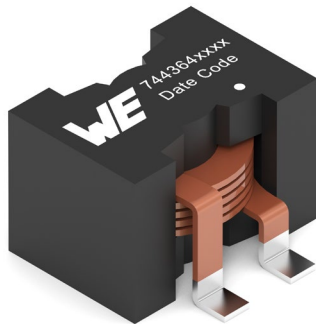
WE-PD



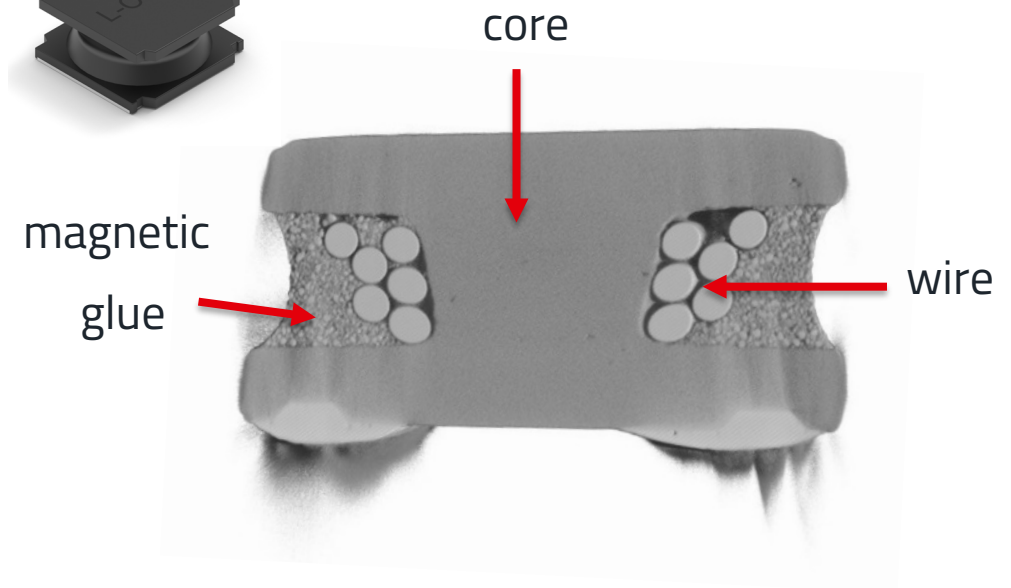
WE-LQS



WE-HCF



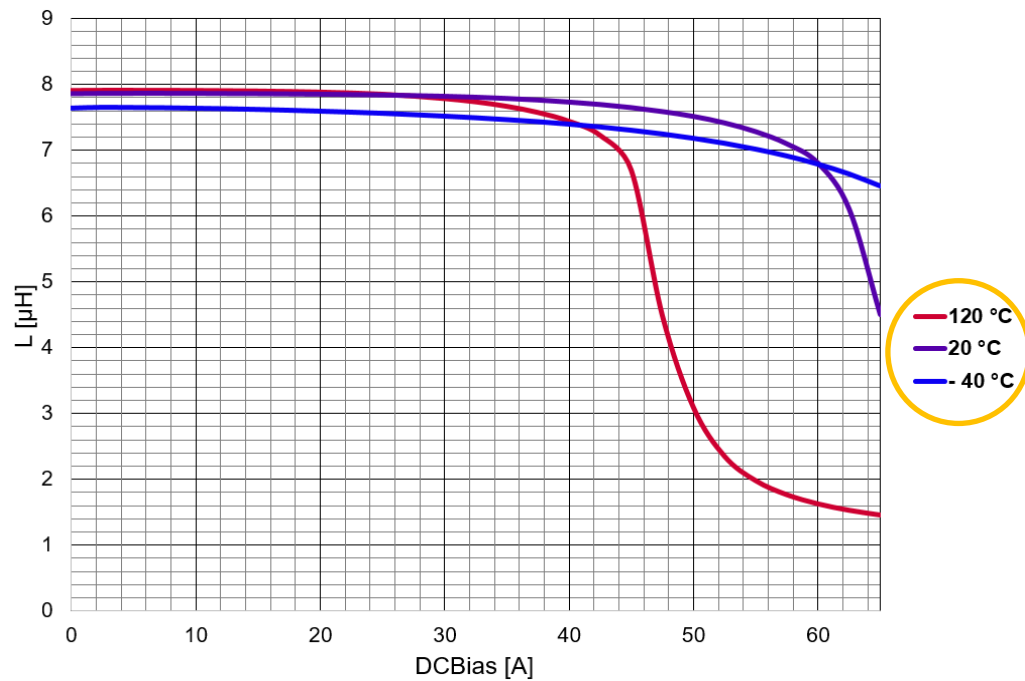
WE-HCFT



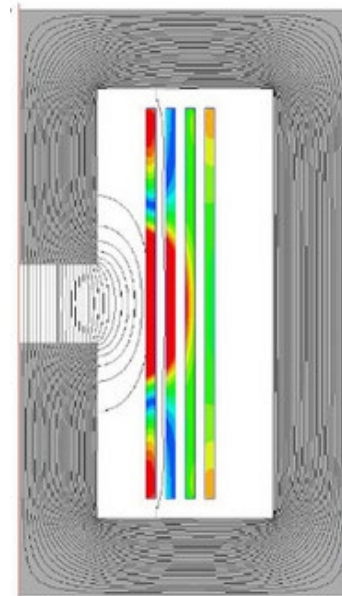
FERRITE BASED POWER INDUCTORS

Disadvantages

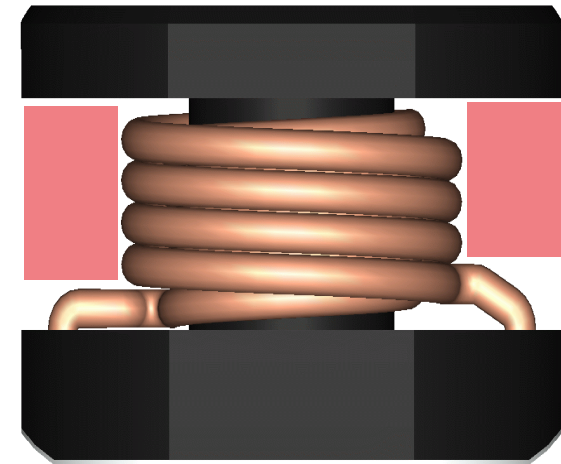
Temperature dependency



Leakage

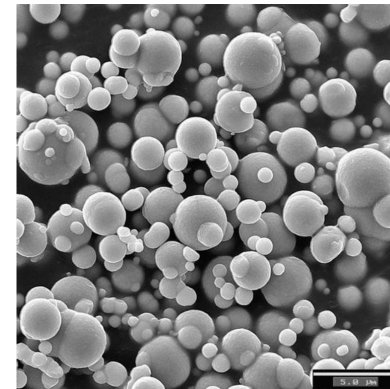
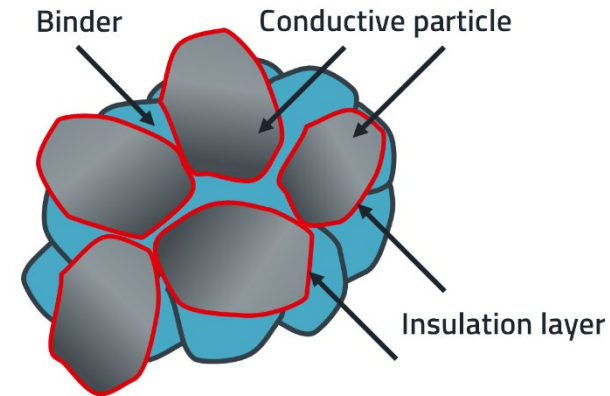


Space utilisation

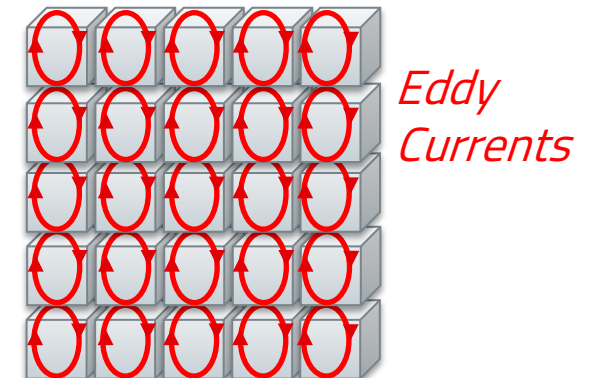


1990S / 2000S

- Frequency range from triple digit kHz up to lower MHz
- Need for more efficient low inductance value products
- Use of iron again, but in powder form
- Same material advantages like massive iron cores, but less eddy currents

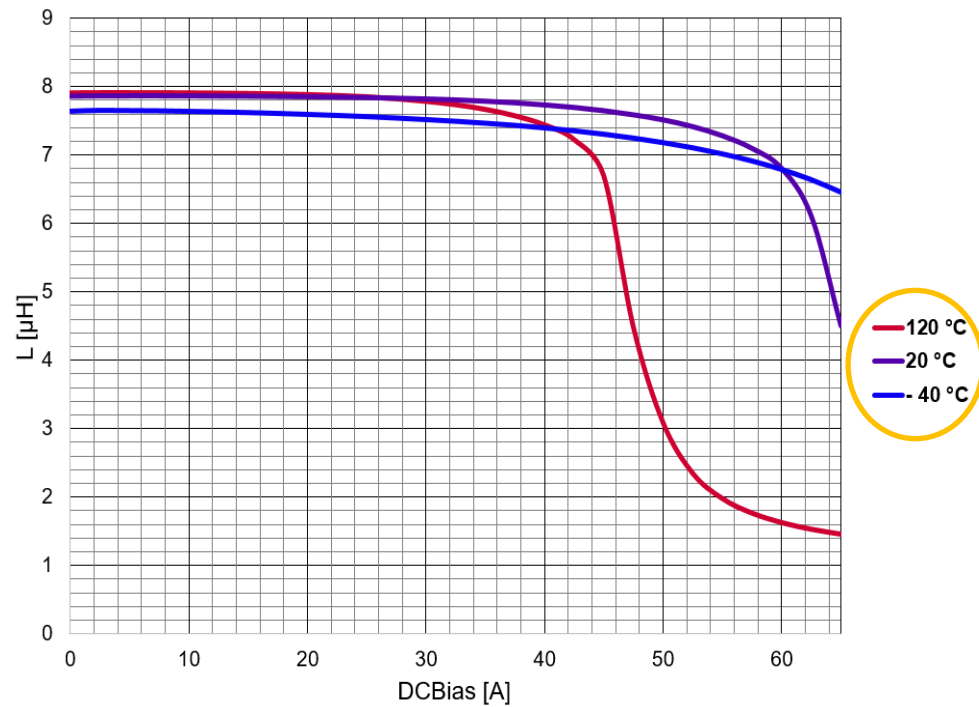


*Iron Powder Particles
- BASF Website*

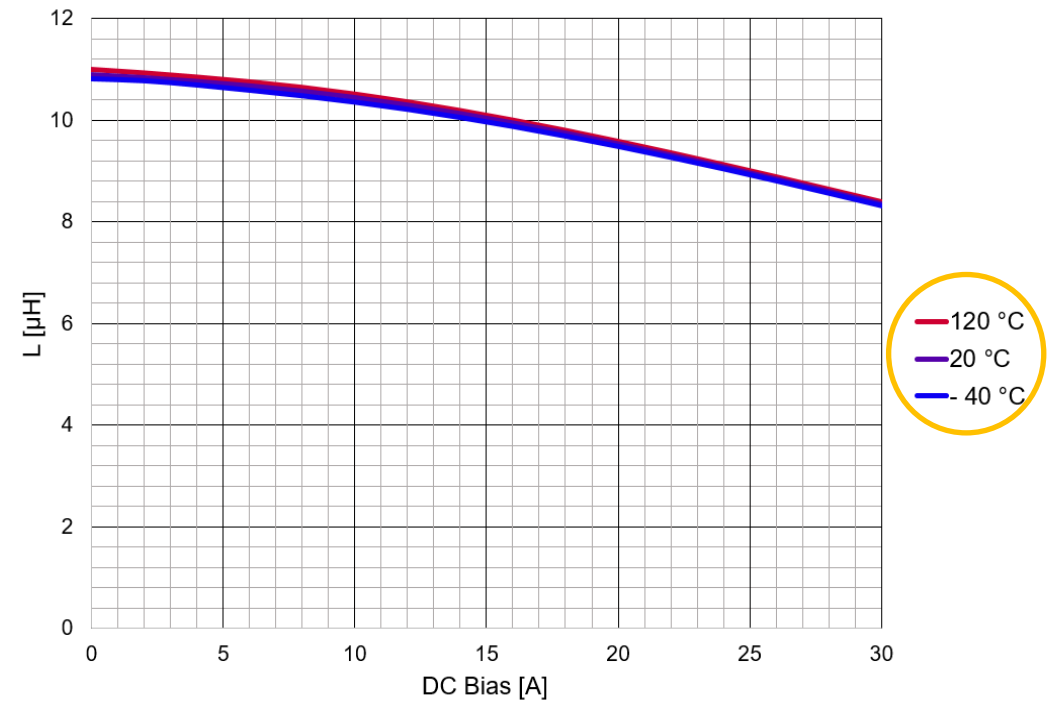


SATURATION BEHAVIOR

Ferrite



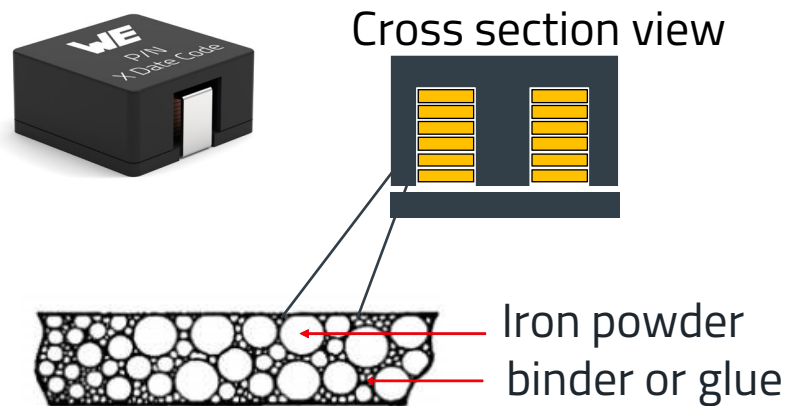
Iron powder



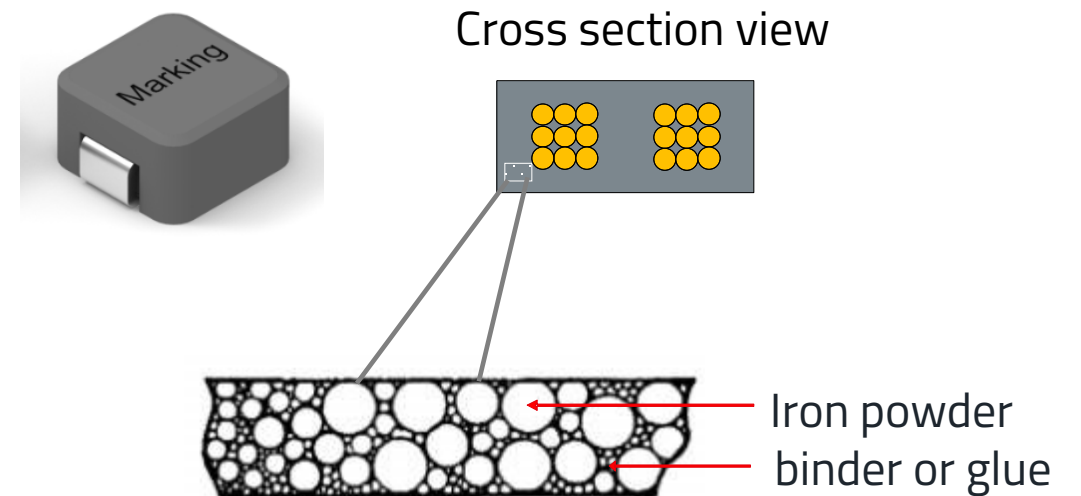
POWDER BASED POWER INDUCTORS

Designs

Assembly products WE-HCI



Molding products WE-LHMI



POWDER BASED POWER INDUCTORS

Materials

- Further requirements on efficiency, current capability and reliability
- Alloys of Iron with Si, Cr, Ni or Al are popular in the market
- Enhanced powder structures known as amorphous or nanocrystalline

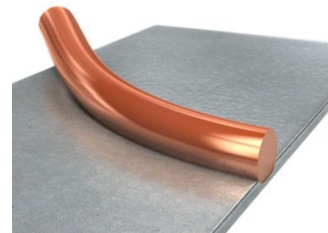
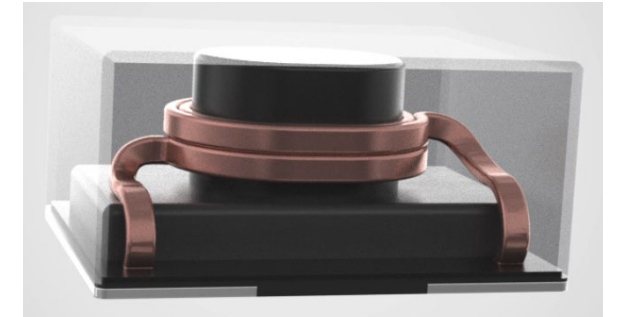
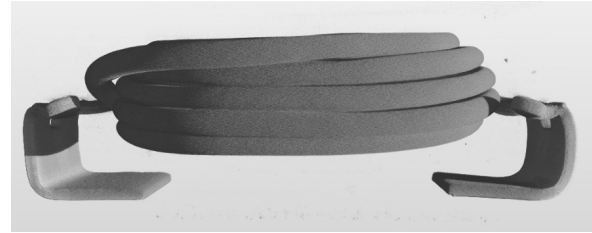


® Registered European Trademark

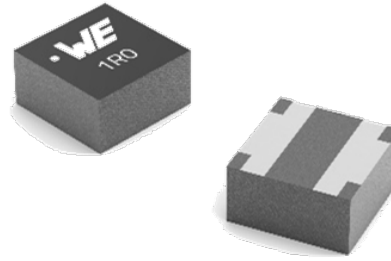
POWDER BASED POWER INDUCTORS

Further optimizations

- Leadframeless designs for better space utilisation
 - E.g. WE-XHMI, WE-PMCI or WE-MAPI
- Mixture of assembly and molding
 - E.g. WE-PMFI
- Production process adjustments for performance improvement
 - E.g. Molding under temperature

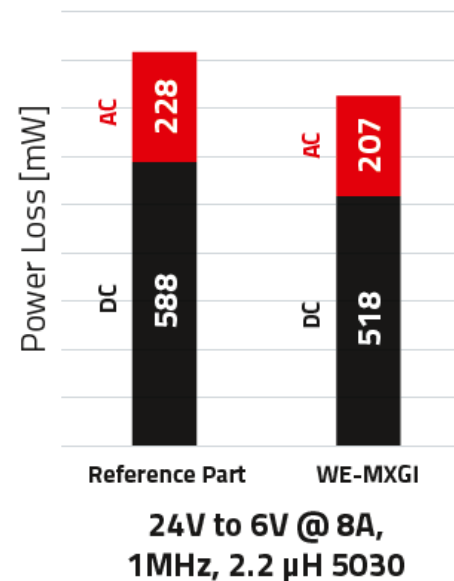


WE-MXGI



- Innovative and high performing product, combining all the mentioned trends in material, design and production technology
- Nanocrystalline core material
- Leadframeless design
- Extremely high power density
- Ultra low RDC values and AC losses
- Optimized for high switching frequencies beyond 1 MHz

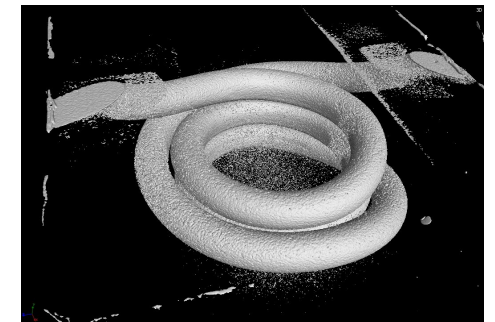
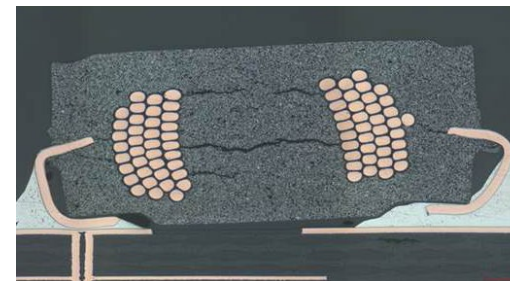
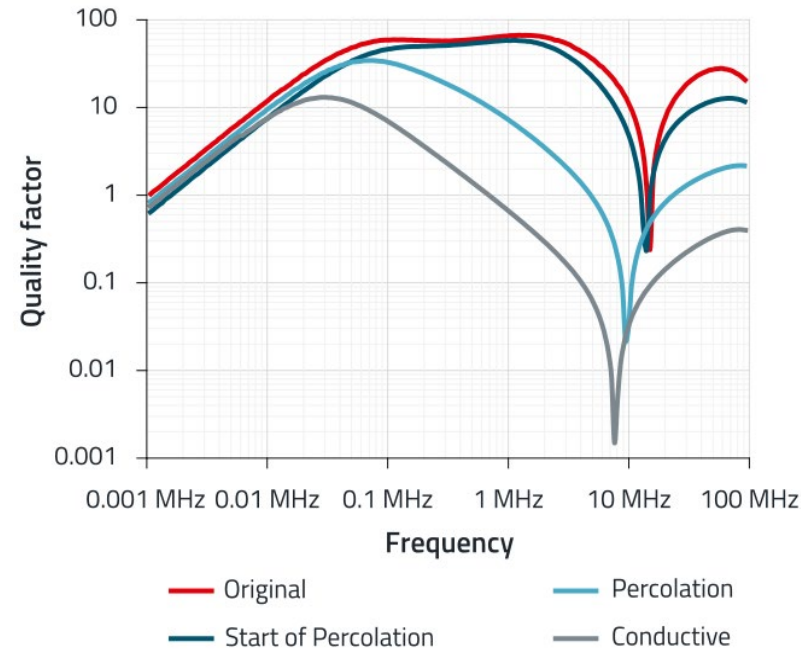
ULTRA LOW POWER LOSSES



FUTURE TRENDS

Limitations with current technologies are...

1. Rough operating conditions
Percolation phenomenon caused by binding and insulation materials
2. Reliability
Internal damage or cracks caused by molding process pressure
3. Lower inductance values
Bad power density caused by poor space utilisation
4. Miniaturisation
Very small structures can't be molded



PLASTIC BASED POWER INDUCTORS

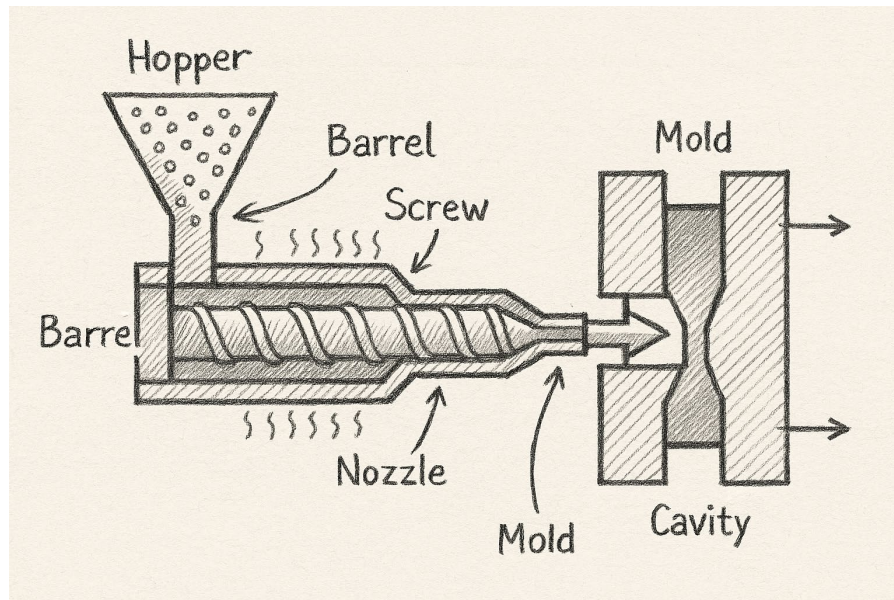
- To avoid percolation the binding and insulation materials need to change
- Can be addressed by switching to inorganic binding and insulation materials
- Using plastics instead of binders, is an approach here
- Additionally this gives the potential of recycling



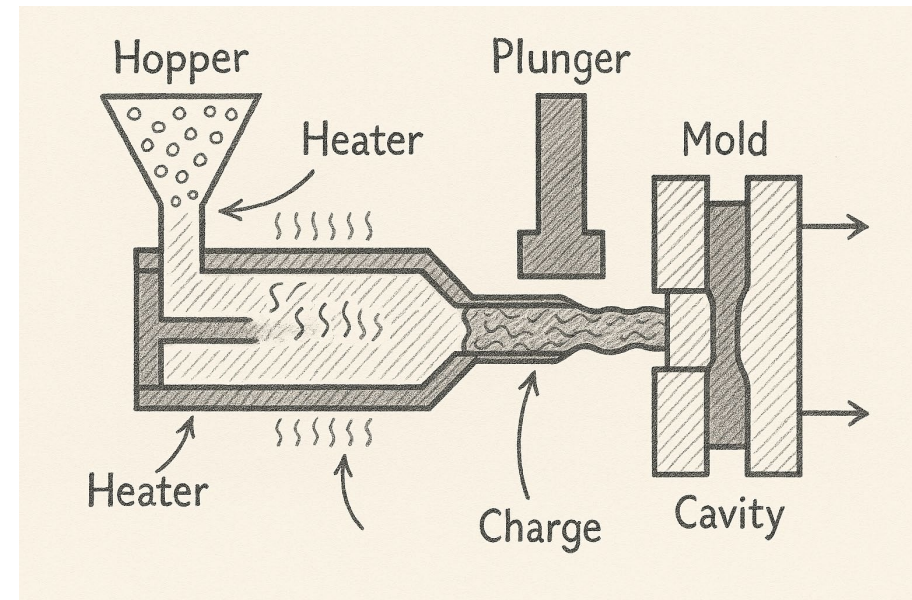
PLASTIC BASED POWER INDUCTORS

Production Process

Injection Molding



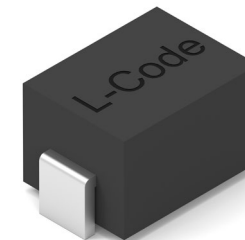
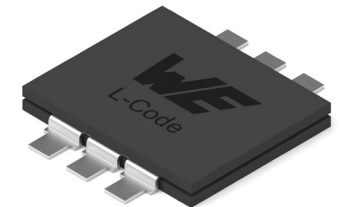
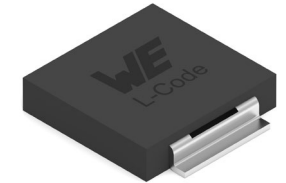
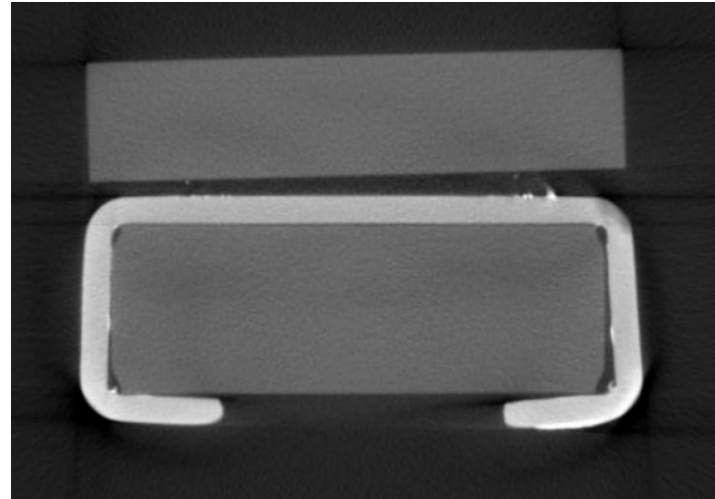
Transfer Molding



CLIP BASED POWER INDUCTORS

Design

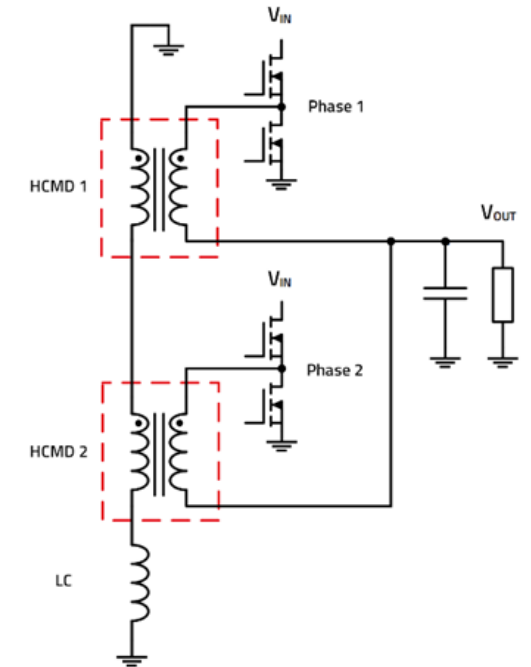
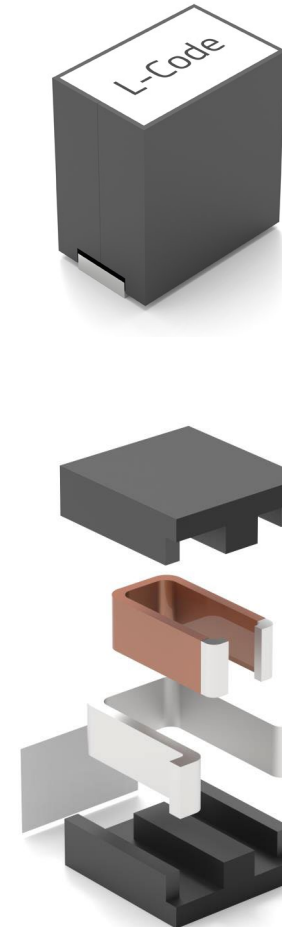
- Low inductance values with clip designs
- Existing products like WE-HCM are based on ferrite
- Highly customized to customer needs
- Transition to powder based solutions



CLIP BASED POWER INDUCTORS

Applications

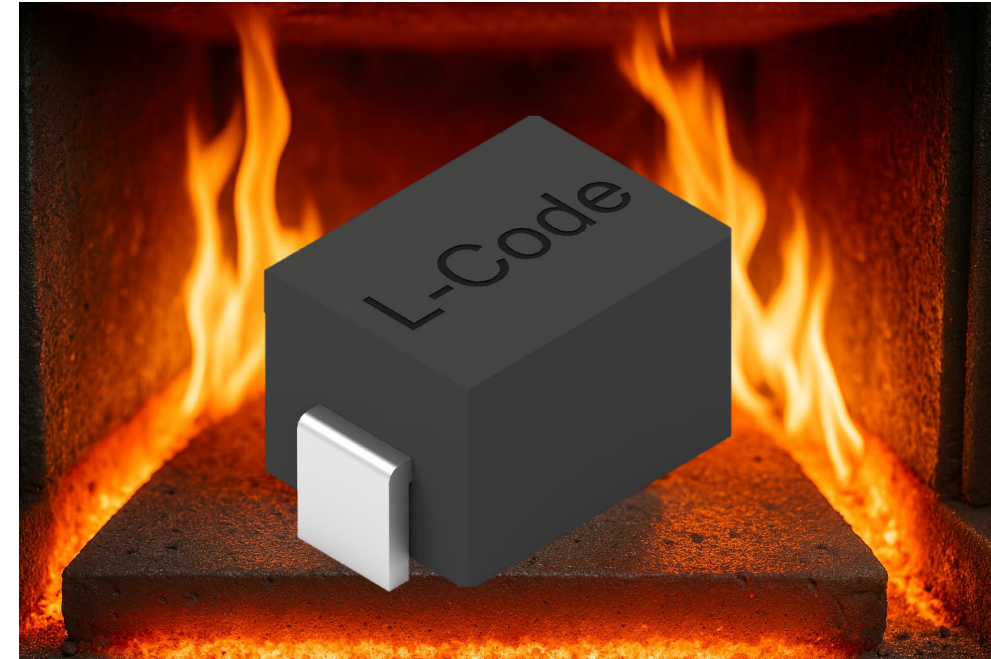
- Main applications are multiphase topologies
- Dual coil designs for TLVR topology
- Trends like vertical power delivery or heat transfer
- Become more and more attractive for high switching frequency applications



CLIP BASED POWER INDUCTORS

Co-sintering

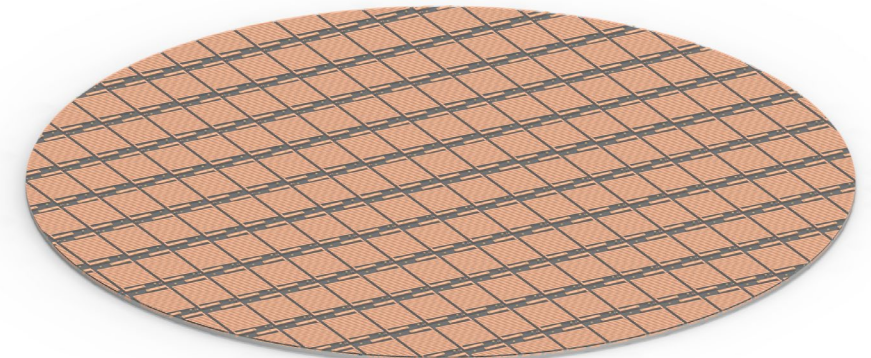
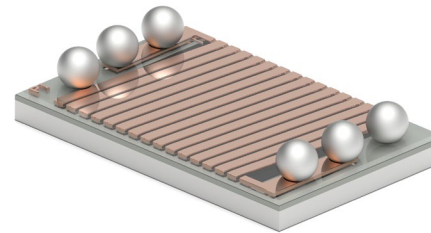
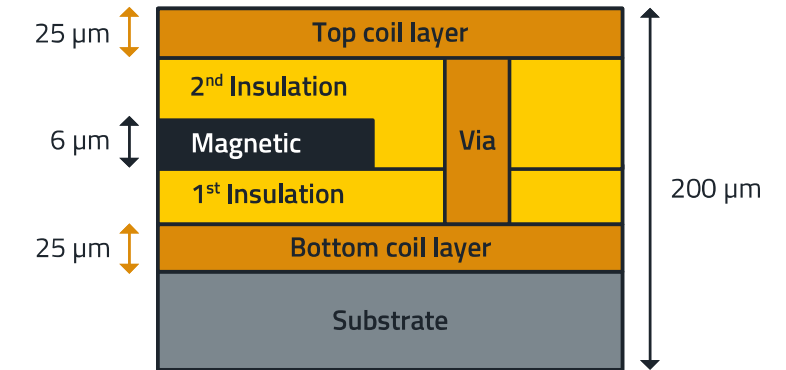
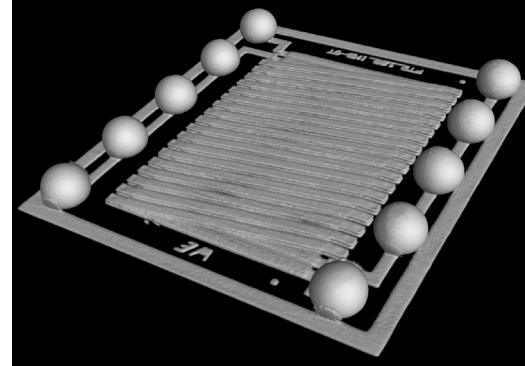
- Powder based solutions
- Classical assembly or molding
- Co-sintering is combining the benefits of assembly materials with the production process of molding
- Exclusively applicable for clip inductors



SILICON BASED POWER INDUCTORS

Design

- For miniaturisation and embedding there is a new technology
- Inductors based on silicon
- Multilayer Construction
- Produced on wafer level like semiconductors

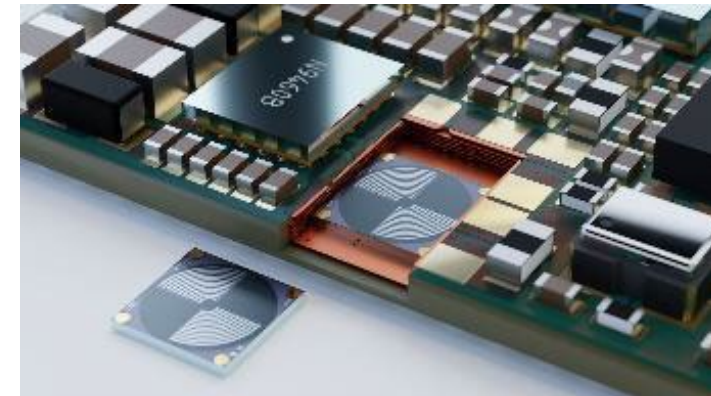
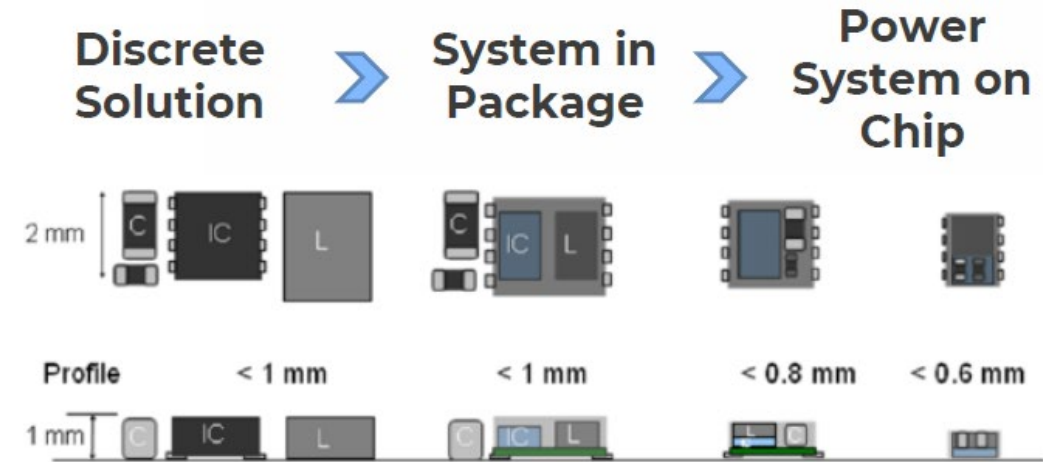


Not to scale!

SILICON BASED POWER INDUCTORS

Processing

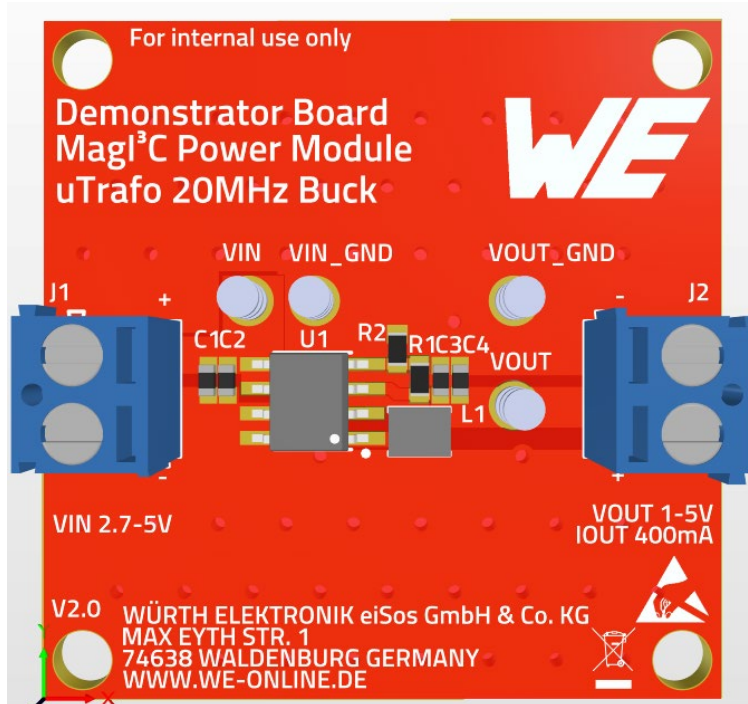
- Different solutions to meet customer processability requirements
- With ball drop for PCB soldering and package in package integration
- Bare die with copper pads for wire bonding or embedding
- Chiplet integration



Source: Open Visions, OV Tech GmbH

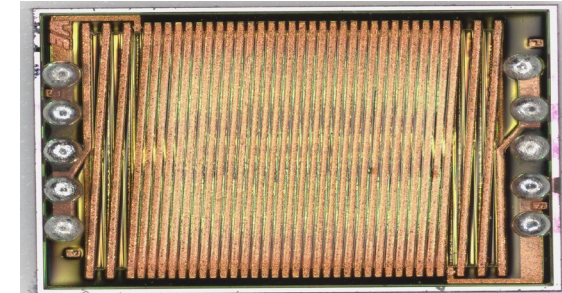
SILICON BASED POWER INDUCTORS

Applications



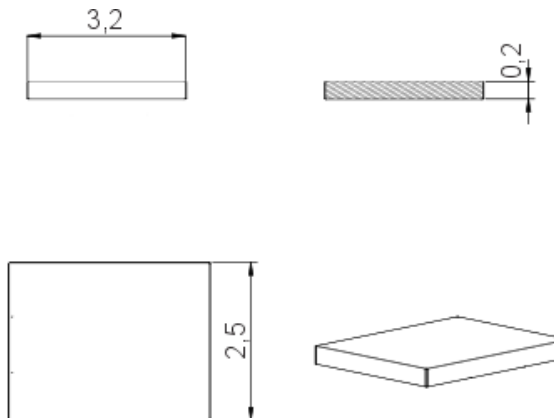
Converter specifications:

- VIN 2.7V – 5V
- VOUT 1V – 5V
- IOUT up to 400mA
- fsw 20MHz



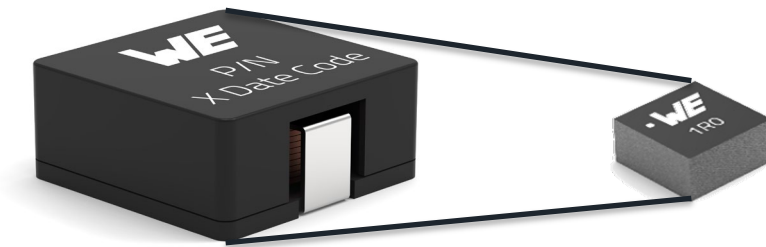
Microtransformer:

- Size 1210
- L = 360nH
- RDC = 1.65Ω
- Isat = 450mA

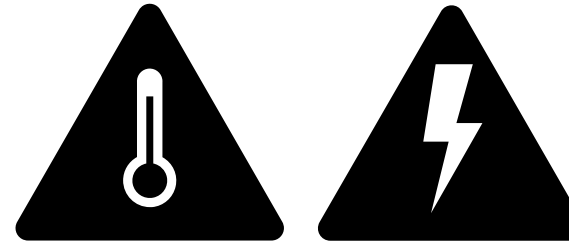


OUTLOOK

Miniaturisation



Harsh environment



High Power



THANK YOU